

μClamp0761ZV μClamp® 1-Line ESD & Surge Protection

PROTECTION PRODUCTS

Description

The μ Clamp0761ZV is a unidirectional TVS specifically designed for single power line protection up to +7.6V. It features large cross-sectional area junctions for conducting high transient currents while occupying minimal board space in a slim 1006(mm) package. Desirable characteristics for board level protection include fast response time, low operating and clamping voltage, and no device degradation. Protection characteristics are highlighted by high surge capability (30A, tp = 8/20µs), low ESD clamping (<10.3V at 30A, tp = 8/20µs) and high ESD withstand voltage (IEC 61000-4-2 Level 4, ±30kV air and contact).

µClamp0761ZV is in a DFN 1.0x0.60x0.25mm-2 Lead package. Leads are spaced at a pitch of 0.65mm and are finished with lead-free NiAu. The combination of small size and high ESD & surge capability makes them ideal for use in applications such as cellular phones, battery protection, and VBUS protection.

Features

- High ESD withstand Voltage: ±30kV (Contact) and ±30kV (Air) per IEC 61000-4-2
- High peak pulse current capability: $30A (tp = 8/20\mu s)$
- Small package(1.0 x 0.6 x 0.25mm)
- Protects one line
- Low ESD clamping voltage
- Working voltage: +7.6V
- Solid-state silicon-avalanche technology

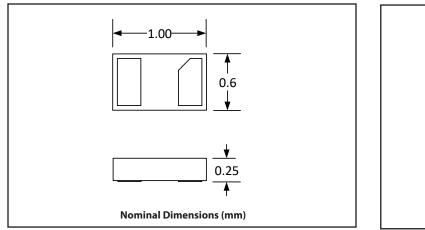
Mechanical Characteristics

- Package: DFN 1.0x0.60x0.25mm-2 Lead
- Pb-Free, Halogen Free, RoHS/WEEE Compliant
- Molding compound flammability rating: UL 94V-0
- Lead Finish: NiAu
- Marking: Marking code
- Packaging: Tape and Reel

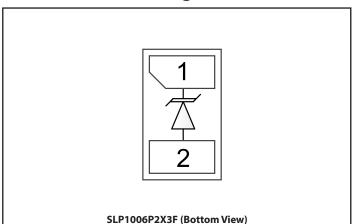
Applications

- Cellular Handsets & Accessories
- Battery Protection
- Notebooks & Handhelds
- USB Voltage Bus

Package Dimension



Schematic & Pin Configuration



Rev 2.1 6/10/2020

Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Power ($t_p = 8/20\mu s$)	P _{PK}	300	W
Peak Pulse Current ($t_p = 8/20\mu s$)	I _{PP}	30	А
ESD per IEC 61000-4-2 (Air) ⁽¹⁾ ESD per IEC 61000-4-2 (Contact) ⁽¹⁾	V _{ESD}	±30 ±30	kV
Operating Temperature	T _{op}	-40 to +85	°C
Storage Temperature	T _{STG}	-55 to +150	°C

Electrical Characteristics (T=25°C unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Reverse Stand-Off Voltage	V _{RWM}	Pin 1 to 2			7.6	V
Reverse Breakdown Voltage	V _{BR}	$I_t = 1$ mA, Pin 1 to 2	7.7	8.2	8.7	V
Reverse Leakage Current	I _R	V _{RWM} = 7.6V, Pin 1 to 2		0.01	0.5	μΑ
Clamping Voltage	V _c	I_{pp} =10A, $t_p = 8/20\mu s$, Pin 1 to 2		8.6	9.1	V
		I_{pp} =25A, t _p = 8/20µs, Pin 1 to 2		9.3	10	
		I_{pp} =30A, t _p = 8/20µs, Pin 1 to 2		9.4	10.3	
ESD Clamping Voltage ²		I _{tip} = 4A, tlp=0.2/100ns, Pin 1 to 2		7.9		
	V _c	I _{ttp} = 16A, tlp=0.2/100ns, Pin 1 to 2		8.1		- V
Dynamic Resistance ^{2,3}	R _{DYN}	tlp = 0.2/100ns		0.02		Ω
Junction Capacitance	C	$V_{R} = 0V, f = 1MHz$		336	400	pF

Notes:

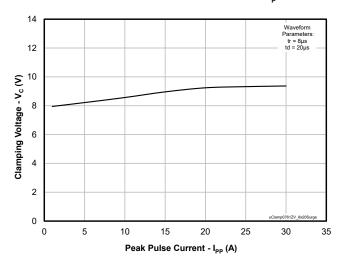
1) ESD gun return path connected to ESD ground plane

2) Transmission Line Pulse Test (TLP) Settings: $t_p = 100ns$, $t_r = 0.2ns$, I_{TLP} and V_{TLP} averaging window: $t_1 = 70ns$ to $t_2 = 90ns$

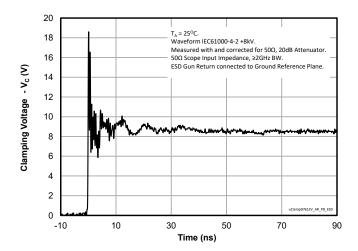
3) Dynamic resistance calculated from $I_{TLP} = 4A$ to $I_{TLP} = 16A$

Typical Characteristics

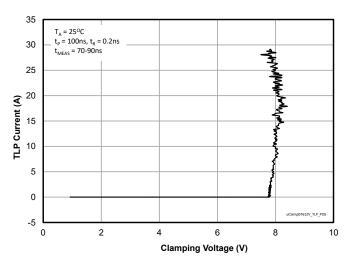
Clamping Voltage vs. Peak Pulse Current (t_p=8/20µs)



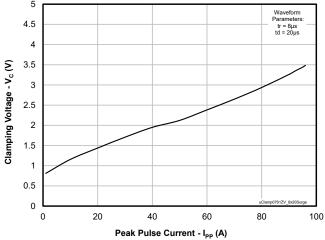
ESD Clamping (+8kV Contact per IEC 61000-4-2)



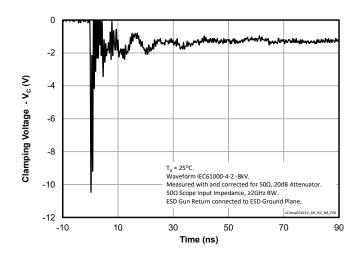
TLP Characteristic (Positive Pulse)



Forward Voltage vs. Peak Pulse Current (t_p=8/20μs)



ESD Clamping (-8kV Contact per IEC 61000-4-2)



µClamp0761ZV Final Datasheet Revision Date

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Application Information

Assembly Guidelines

The small size of this device means that some care must be taken during the mounting process to ensure reliable solder joints. The figure at the right details Semtech's recommended mounting pattern. Recommended assembly guidelines are shown in Table 1. Note that these are only recommendations and should serve only as a starting point for design since there are many factors that affect the assembly process. Exact manufacturing parameters will require some experimentation to get the desired solder application.

Solder Stencil

Stencil design is one of the key factors which will determine the volume of solder paste which is deposited onto the land pad. The area ratio of the stencil aperture will determine how well the stencil will print. The area ratio takes into account the aperture shape, aperture size, and stencil thickness. A minimum area ratio of 0.66 is preferred for the subject package. The area ratio of a rectangular aperture is given as:

Area Ratio = (L * W) / (2 * (L + W) * T)

Where:

L = Aperture Length W = Aperture Width T = Stencil Thickness

Semtech recommends a stencil with square aperture and rounded corners for consistent solder release. The stencil should be laser cut with electro-polished finish. A stencil thickness of 0.100mm (0.004") or 0.125mm (0.005") stencil may be used, however the stencil opening may need to be increased slightly to achieve the desired area ratio to ensure proper solder coverage on the pad.

Recommended Mounting Pattern

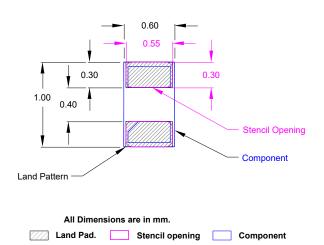
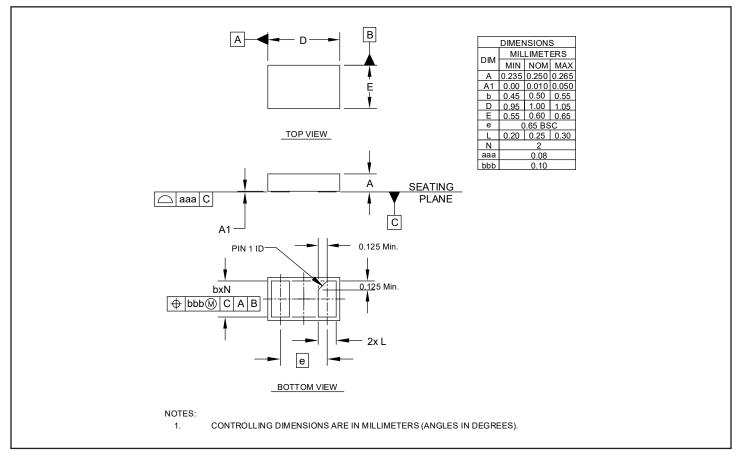


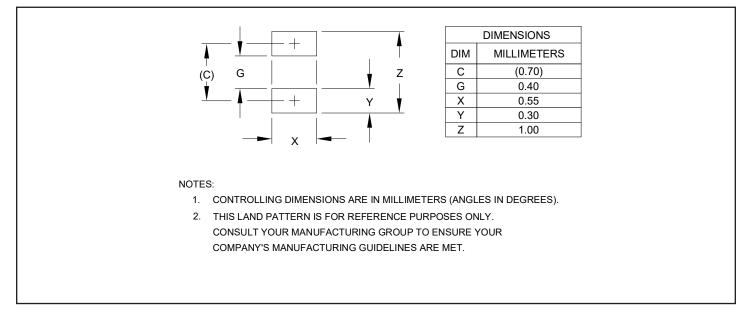
Table 1 - Assembly Guidelines

Table 1 Assembly Guidennes					
Assembly Parameter	Recommendation				
Solder Stencil Design	Laser Cut, Electro-Polished				
Aperture Shape	Rectangular with				
	Rounded Corners				
Solder Stencil Thickness	0.100mm (0.004") or				
	0.125mm (0.005")				
Solder Paste Type	Type 4 or Type 5				
Solder Reflow Profile	Per JEDEC J-STD-020				
PCB Solder Pad Design	SMD or NSMD				
PCB Pad Finish	OSP or NiAu				

Outline Drawing - DFN 1.0x0.60x0.25mm-2 Lead

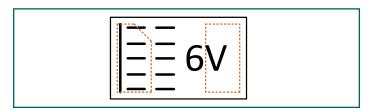


Land Pattern - DFN 1.0x0.60x0.25mm-2 Lead



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Marking Code

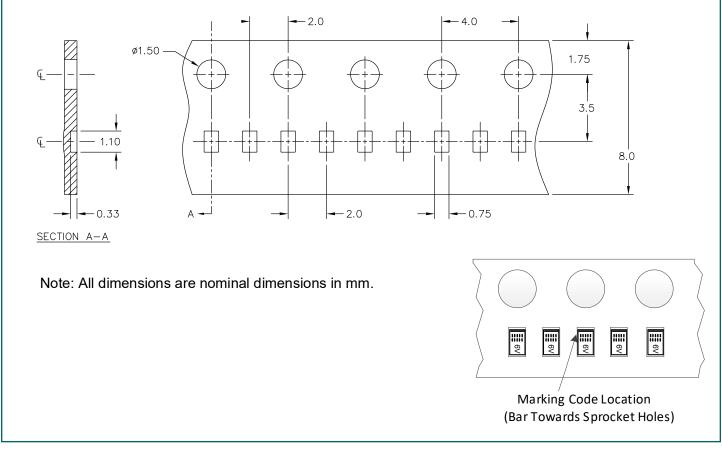


Notes:

1. Marking will also include line matrix date code.

2. Bar indicates Pin 1 location.

Tape and Reel Specification



Ordering Information

Part Number	Qty per Reel	Reel Size
µClamp0761ZVTFT	15,000	7″



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